Session Title:	[MC1] Advanced Ceria-Abrasive Based CMP
Session Date:	November 20 (Mon.), 2023
Session Time:	13:00-14:40
Session Room:	Room C (Grand Ballroom 2, 2F)
Session Chair:	Prof. Tae Dong Kim (Hannam Univ., Korea)

[MC1-1] [Invited] 13:00-13:20

Polishing Mechanism on Ceria/SiO_2 Interface

Satoyuki Nomura (Resonac Corp., Japan)

[MC1-2] 13:20-13:40

Remarkable SiO_2-Film Polishing-Rate Enhancement Using Wet-Ceria-Abrasives Based Chemical-Mechanical-Planarization Slurry and Radical Oxidation

Pil-Su Kim, Min-Uk Jeon, Hyeong-Ju Jin, Ho-Jun Ahn, Ju-Yeon Kim (Hanyang Univ., Korea), Jin-Hyung Park (ENF Tech. Inc., Korea), and Jea-Gun Park (Hanyang Univ., Korea)

[MC1-3] 13:40-14:00

Ce^{3+} Enriched Ceria Nanoparticles for Silicate Adsorption

Sungmin Kim, Ganggyu Lee, Donghwan Kim, Myungju Woo, Yeram Lee, Hongjun Park, Bobae Lee, Taeseup Song, and Ungyu Paik (Hanyang Univ., Korea)

[MC1-4] 14:00-14:20

Nano Cerium Oxide Slurry for Scratch Free with High Selectivity in Various Film

Jeong Ho Lee and Seok Joo Kim (Soulbrain, Korea)

[MC1-5] 14:20-14:40

Super-Fine CeO_2 Abrasives Having 4-nm in Diameter Synthesized via Oxidation Reaction between Trivalent Cerium and H_2O_2

Min-Uk Jeon, Pil-Su Kim, Hyeong-Ju Jin, Ho-Jun Ahn, Ju-Yeon Kim (Hanyang Univ., Korea), Jin-Hyung Park (ENF Tech. Inc., Korea), and Jea-Gun Park (Hanyang Univ., Korea)